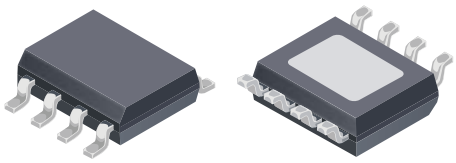
Full-Bridge DMOS PWM Motor Driver

Features and Benefits

- Low $R_{DS(on)}$ outputs
- Overcurrent protection (OCP)
  - Motor short protection
  - Motor lead short to ground protection
  - Motor lead short to battery protection
- Low Power Standby mode
- Adjustable PWM current limit
- Synchronous rectification
- Internal undervoltage lockout (UVLO)
- Crossover-current protection

Package: 8-pin SOICN with exposed thermal pad (suffix LJ)



Not to scale

Description

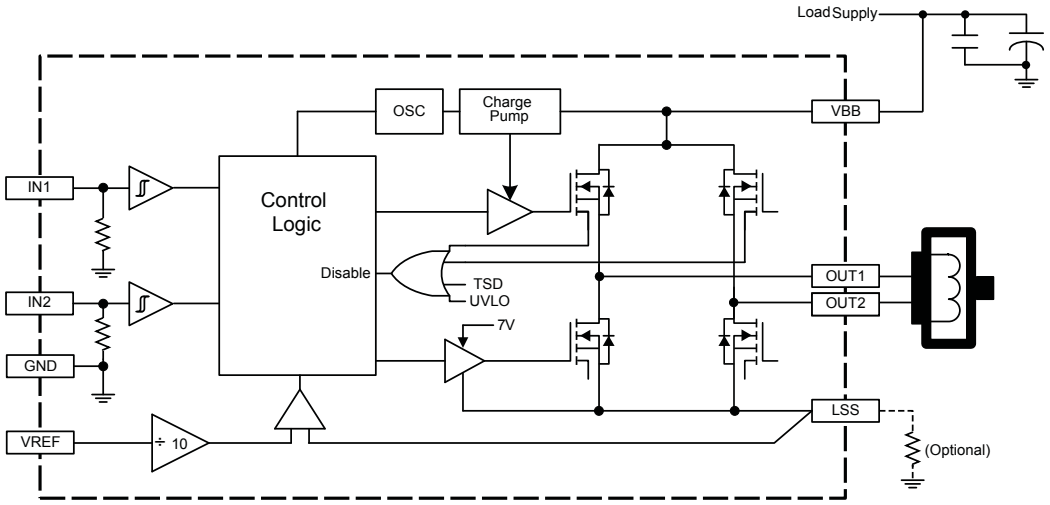
Designed for pulse width modulated (PWM) control of DC motors, the A4950 is capable of peak output currents to ±3.5 A and operating voltages to 40 V.

Input terminals are provided for use in controlling the speed and direction of a DC motor with externally applied PWM control signals. Internal synchronous rectification control circuitry is provided to lower power dissipation during PWM operation.

Internal circuit protection includes overcurrent protection, motor lead short to ground or supply, thermal shutdown with hysteresis, undervoltage monitoring of V_{BB}, and crossover-current protection.

The A4950 is provided in a low-profile 8-pin SOICN package with exposed thermal pad (suffix LJ) that is lead (Pb) free, with 100% matte tin leadframe plating.

Functional Block Diagram



Selection Guide

Part Number	Packing
A4950ELJTR-T	3000 pieces per 13-in. reel

Absolute Maximum Ratings

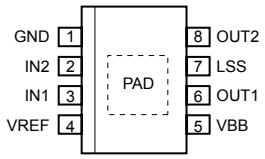
Characteristic	Symbol	Notes	Rating	Unit
Load Supply Voltage	V_{BB}		40	V
Logic Input Voltage Range	V_{IN}		–0.3 to 6	V
V_{REF} Input Voltage Range	V_{REF}		–0.3 to 6	V
Sense Voltage (LSS pin)	V_S		–0.5 to 0.5	V
Motor Outputs Voltage	V_{OUT}		–2 to 42	V
Output Current	I_{OUT}	Duty cycle = 100%	3.5	A
Transient Output Current	i_{OUT}	T_W < 500 ns	6	A
Operating Temperature Range	T_A	Temperature Range E	–40 to 85	°C
Maximum Junction Temperature	T_J(max)		150	°C
Storage Temperature Range	T_{stg}		–55 to 150	°C

Thermal Characteristics may require derating at maximum conditions, see application information

Characteristic	Symbol	Test Conditions*	Value	Unit
Package Thermal Resistance	$R_{\theta JA}$	On 2-layer PCB with 0.8 in.² exposed 2-oz. copper each side	62	ºC/W
		On 4-layer PCB based on JEDEC standard	35	ºC/W

*Additional thermal information available on the Allegro website.

Pin-out Diagram



Terminal List Table

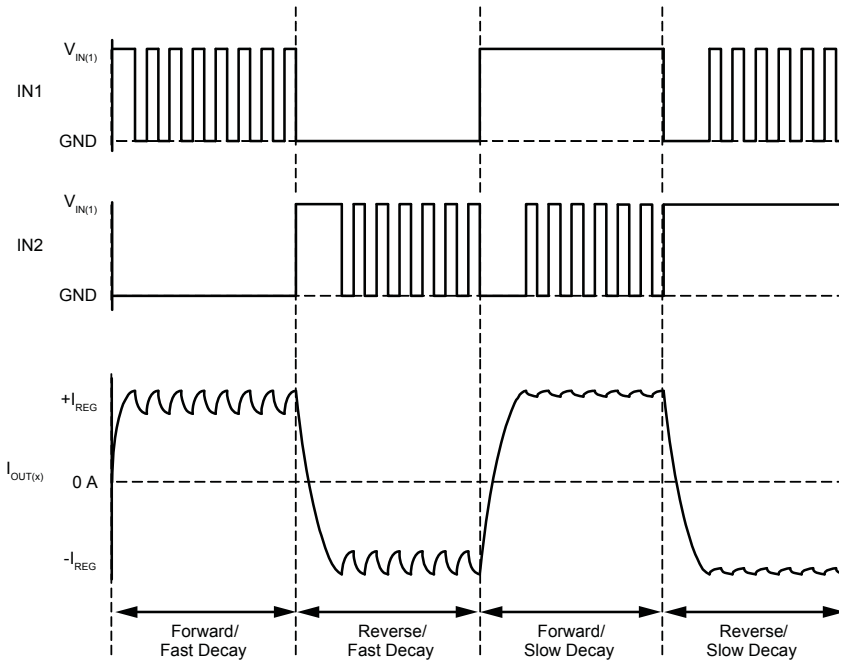
Number	Name	Function
1	GND	Ground
2	IN2	Logic input 2
3	IN1	Logic input 1
4	VREF	Analog input
5	VBB	Load supply voltage
6	OUT1	DMOS full bridge output 1
7	LSS	Power return – sense resistor connection
8	OUT2	DMOS full bridge output 2
–	PAD	Exposed pad for enhanced thermal dissipation

ELECTRICAL CHARACTERISTICS Valid at T_J = 25°C, unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
General						
Load Supply Voltage Range	V_{BB}		8	–	40	V
$R_{DS(on)}$ Sink + Source Total	$R_{DS(on)}$	I_{OUT} = |2.5 A|, T_J = 25°C	–	0.6	0.8	Ω
		I_{OUT} = |2.5 A|, T_J = 125°C	–	0.96	1.3	Ω
Load Supply Current	I_{BB}	f_{PWM} < 30 kHz	–	10	–	mA
		Low Power Standby mode	–	–	10	µA
Body Diode Forward Voltage	V_f	Source diode, I_f = –2.5 A	–	–	1.5	V
		Sink diode, I_f = 2.5 A	–	–	1.5	V
Logic Inputs						
Logic Input Voltage Range	$V_{IN(1)}$		2.0	–	–	V
	$V_{IN(0)}$		–	–	0.8	V
	$V_{IN(STANDBY)}$	Low Power Standby mode	–	–	0.4	V
Logic Input Current	$I_{IN(1)}$	V_{IN} = 2.0 V	–	40	100	µA
	$I_{IN(0)}$	V_{IN} = 0.8 V	–	16	40	µA
Logic Input Pull-Down Resistance	$R_{LOGIC(PD)}$	V_{IN} = 0 V = IN1 = IN2	–	50	–	kΩ
Input Hysteresis	V_{HYS}		–	250	550	mV
Timing						
Crossover Delay	t_{COD}		50	–	500	ns
V_{REF} Input Voltage Range	V_{REF}		0	–	5	V
Current Gain	A_V	V_{REF} / I_{SS}, V_{REF} = 5 V	9.5	–	10.5	V/V
		V_{REF} / I_{SS}, V_{REF} = 2.5 V	9.0	–	10.0	V/V
		V_{REF} / I_{SS}, V_{REF} = 1 V	8.0	–	10.0	V/V
Blank Time	t_{BLANK}		2	3	4	µs
Constant Off-time	t_{off}		16	25	34	µs
Standby Timer	t_{st}	IN1 = IN2 < $V_{IN(STANDBY)}$	–	1	1.5	ms
Power-Up Delay	t_{pu}		–	–	30	µs
Protection Circuits						
UVLO Enable Threshold	V_{BBUVLO}	V_{BB} increasing	7	7.5	7.95	V
UVLO Hysteresis	$V_{BBUVLOhys}$		–	500	–	mV
Thermal Shutdown Temperature	T_{JTSD}	Temperature increasing	–	160	–	°C
Thermal Shutdown Hysteresis	T_{TSDhys}	Recovery = T_{JTSD} – T_{TSDhys}	–	15	–	°C

Characteristic Performance

PWM Control Timing Diagram



PWM Control Truth Table

IN1	IN2	$10 \times V_S > V_{REF}$	OUT1	OUT2	Function
0	1	False	L	H	Reverse
1	0	False	H	L	Forward
0	1	True	H/L	L	Chop (mixed decay), reverse
1	0	True	L	H/L	Chop (mixed decay), forward
1	1	False	L	L	Brake (slow decay); after a Chop command
0	0	False	Z	Z	Coast, enters Low Power Standby mode after 1 ms

Note: Z indicates high impedance.

Functional Description

Device Operation

The A4950 is designed to operate DC motors. The output drivers are all low-$R_{DS(on)}$, N-channel DMOS drivers that feature internal synchronous rectification to reduce power dissipation. The current in the output full bridge is regulated with fixed off-time pulse width modulated (PWM) control circuitry. The IN1 and IN2 inputs allow two-wire control for the bridge.

Protection circuitry includes internal thermal shutdown, and protection against shorted loads, or against output shorts to ground or supply. Undervoltage lockout prevents damage by keeping the outputs off until the driver has enough voltage to operate normally.

Standby Mode

Low Power Standby mode is activated when both input (INx) pins are low for longer than 1 ms. Low Power Standby mode disables most of the internal circuitry, including the charge pump and the regulator. When the A4950 is coming out of standby mode, the charge pump should be allowed to reach its regulated voltage (a maximum delay of 200 µs) before any PWM commands are issued to the device.

Internal PWM Current Control

Initially, a diagonal pair of source and sink FET outputs are enabled and current flows through the motor winding and the optional external current sense resistor, R_S. When the voltage across R_S equals the comparator trip value, then the current sense comparator resets the PWM latch. The latch then turns off the sink and source FETs (Mixed Decay mode).

V_{REF}

The maximum value of current limiting is set by the selection of R_{Sx} and the voltage at the VREF pin. The transconductance function is approximated by the maximum value of current limiting, $I_{TripMAX}$ (A), which is set by:

$$I_{TripMAX} = \frac{V_{REF}}{10 \times R_S}$$

where V_{REF} is the input voltage on the VREF pin (V) and R_S is the resistance of the sense resistor (Ω) on the LSS terminal.

Overcurrent Protection

A current monitor will protect the IC from damage due to output shorts. If a short is detected, the IC will latch the fault and disable the outputs. The fault latch can only be cleared by coming out of Low Power Standby mode or by cycling the power to VBB. During OCP events, Absolute Maximum Ratings may be exceeded for a short period of time before the device latches.

Shutdown

If the die temperature increases to approximately 160°C, the full bridge outputs will be disabled until the internal temperature falls below a hysteresis, T_{TSDhys}, of 15°C. Internal UVLO is present on VBB to prevent the output drivers from turning-on below the UVLO threshold.

Braking

The braking function is implemented by driving the device in Slow Decay mode, which is done by applying a logic high to both inputs, after a bridge-enable Chop command (see PWM Control Truth Table). Because it is possible to drive current in both directions through the DMOS switches, this configuration effectively shorts-out the motor-generated BEMF, as long as the Chop command is asserted. The maximum current can be approximated by V_{BEMF} / R_L. Care should be taken to ensure that the maximum ratings of the device are not exceeded in worse case braking situations: high speed and high-inertia loads.

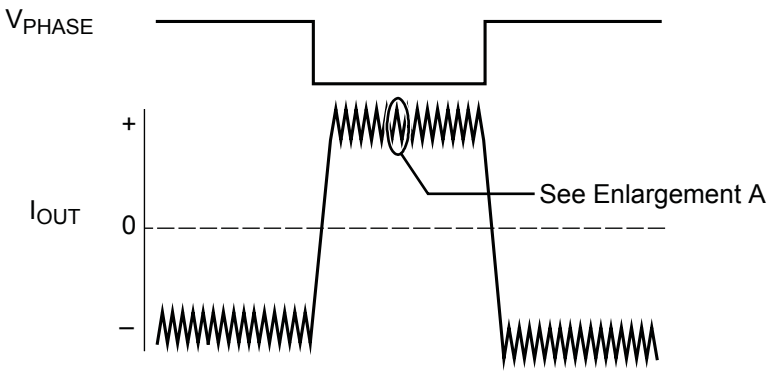
Synchronous Rectification

When a PWM off-cycle is triggered by an internal fixed off-time cycle, load current will recirculate. The A4950 synchronous rectification feature turns-on the appropriate DMOSFETs during the current decay, and effectively shorts out the body diodes with the low $R_{DS(on)}$ driver. This significantly lowers power dissipation. When a zero current level is detected, synchronous rectification is turned off to prevent reversal of the load current.

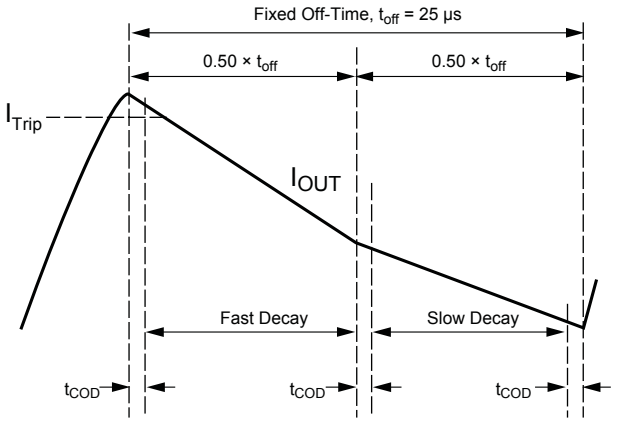
Mixed Decay Operation

The bridges operate in Mixed Decay mode. Referring to the lower panel of the figure below, as the trip point is reached, the device goes into fast decay mode for 50% of the fixed off-time period. After this fast decay portion the device switches to slow decay mode for the remainder of the off-time. During transitions from fast decay to slow decay, the drivers are forced off for the Crossover Delay, t_{COD}. This feature is added to prevent shoot-through in the bridge. During this "dead time" portion, synchronous rectification is not active, and the device operates in fast decay and slow decay only.

Mixed Decay Mode Operation



Enlargement A



Application Information

Sense Pin (LSS)

In order to use PWM current control, a low-value resistor is placed between the LSS pin and ground for current sensing purposes. To minimize ground-trace IR drops in sensing the output current level, the current sensing resistor should have an independent ground return to the star ground point. This trace should be as short as possible. For low-value sense resistors, the IR drops in the PCB can be significant, and should be taken into account.

When selecting a value for the sense resistor be sure not to exceed the maximum voltage on the LSS pin of ±500 mV at maximum load. During overcurrent events, this rating may be exceeded for short durations.

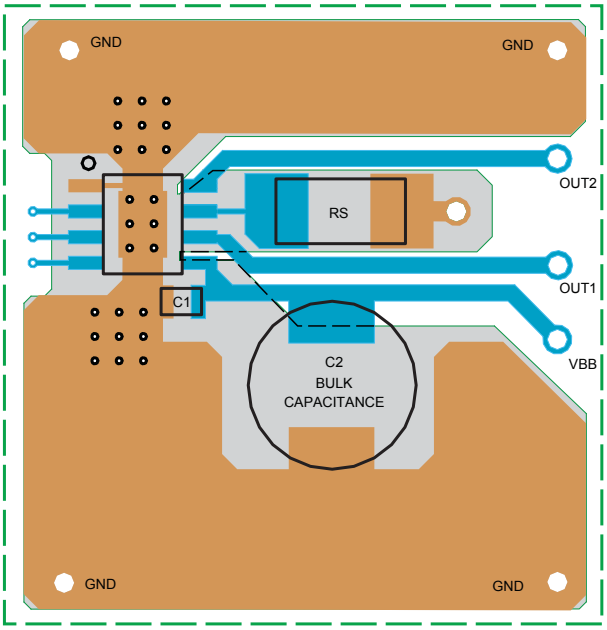
Ground

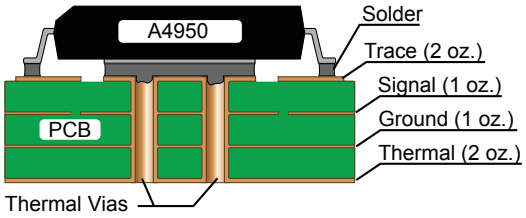
A star ground should be located as close to the A4950 as possible. The copper ground plane directly under the exposed thermal pad of the device makes a good location for the star ground point. The exposed pad can be connected to ground for this purpose.

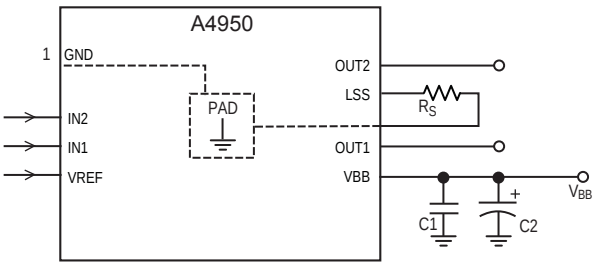
Layout

The PCB should have a thick ground plane. For optimum electrical and thermal performance, the A4950 must be soldered directly onto the board. On the underside of the A4950 package is an exposed pad, which provides a path for enhanced thermal dissipation. The thermal pad must be soldered directly to an exposed surface on the PCB in order to achieve optimal thermal conduction. Thermal vias are used to transfer heat to other layers of the PCB.

The load supply pin, VBB, should be decoupled with an electrolytic capacitor (typically 100 µF) in parallel with a lower valued ceramic capacitor placed as close as practicable to the device.



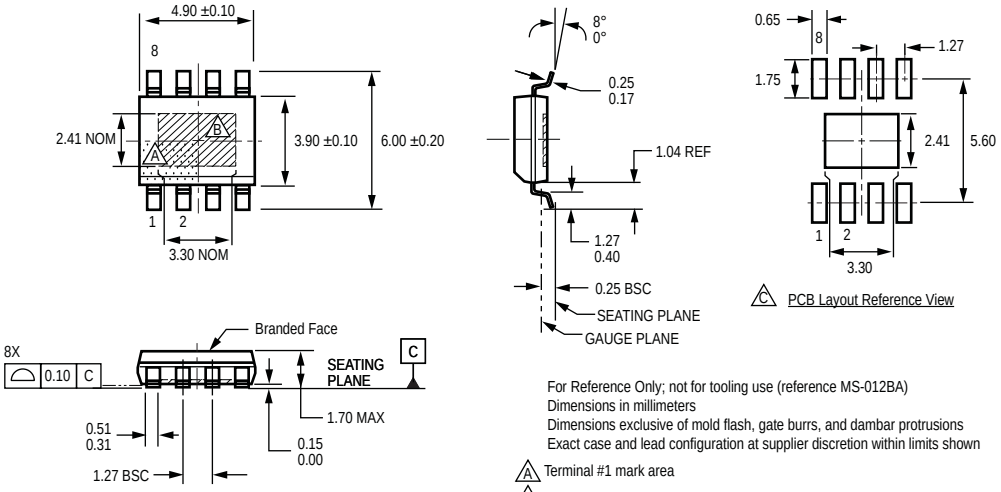




Bill of Materials

Item	Reference	Value	Units	Description
1	RS	0.25 (for V_{REF} = 5 V, I_{OUT} = 2 A)	Ω	2512, 1 W, 1% or better, carbon film chip resistor
2	C1	0.22	µF	X5R minimum, 50 V or greater
3	C2	100	µF	Electrolytic, 50 V or greater

Package LJ, 8-Pin SOICN with exposed thermal pad



For Reference Only; not for tooling use (reference MS-012BA)
Dimensions in millimeters
Dimensions exclusive of mold flash, gate burrs, and dambar protrusions
Exact case and lead configuration at supplier discretion within limits shown

A Terminal #1 mark area

B Exposed thermal pad (bottom surface); dimensions may vary with device

C Reference land pattern layout (reference IPC7351 SOIC127P600X175-9AM); all pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5)

Revision History

Revision	Revision Date	Description of Revision
Rev. 2	November 9, 2011	Update PWM timing, A_V

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